

## **Leaders in 3D Packaging Equipment Announce Seminar Series on Integrated Process Solutions**

**Munich, September 25<sup>th</sup>** - NEXX Systems, Surface Technology Systems (STS), and SUSS MicroTec today announced they will collaborate with Fraunhofer IZM to demonstrate integrated process solutions for 3D wafer level packaging. As a first action, a series of seminars has been scheduled from October 26 to November 7, 2007. The seminars will be held in Singapore, Japan, China, Korea, and Taiwan and are targeted at packaging industry professionals involved in 3D packaging applications.

The seminars will cover optimization of integrated process solutions from the point of view of performance and cost. Leading edge total process solutions for 3D wafer level packaging will be demonstrated by combining the expertise of STS in deep reactive ion etch (DRIE) for via fabrication, NEXX Systems in PVD and Electrodeposition for lining and filling of vias, and SUSS MicroTec in wafer bonding and photolithography. Fraunhofer IZM will complement these strengths with their extensive expertise in 3D wafer level packaging, acting as both a consultant and active participant in the integration of process solutions.

More detailed information is available at [www.3dintegration.org](http://www.3dintegration.org)

**About Surface Technology Systems plc:** STS is a leading provider of specialist plasma etch and deposition systems to customers in the MEMS, wafer level packaging, optoelectronic, compound semiconductor, and thin film head industries. Additional information can be found at: [www.stsystems.com](http://www.stsystems.com).

**About Suss MicroTec:** SUSS MicroTec is a global supplier of production and test equipment for the semiconductor and related industries. Suss equipment is used by leading semiconductor manufacturers as well as renowned research institutes to make and test state-of-the art microchips and sensors. Many of the products you use in your daily life such as PDA's, GPS systems, cell phones etc. have at sometime been touched by equipment from SUSS MicroTec. Additional information can be found at: [www.suss.com](http://www.suss.com).

**About Fraunhofer IZM:** Fraunhofer Institute for Reliability and Microintegration are dedicated to keeping suppliers and users of products designed for system integration and packaging of electronic products on top of technological developments, thus enabling manufacturers to maintain their competitive edge. Additional information can be found at: [www.izm.fhg.de](http://www.izm.fhg.de).

**About NEXX Systems:** NEXX Systems brings exceptional technical expertise to flip chip and advanced packaging. Our product lines provide the most efficient, yet affordable, systems of their kind: Nimbus for multi-layer sputter deposition of metals, and Stratus for high throughput electro-deposition of metals. Additional information can be found at: [www.nexxsystems.com](http://www.nexxsystems.com).